Kingbright

1.6X0.8mm SMD CHIP LED LAMP

AP1608SURCK HYPER RED

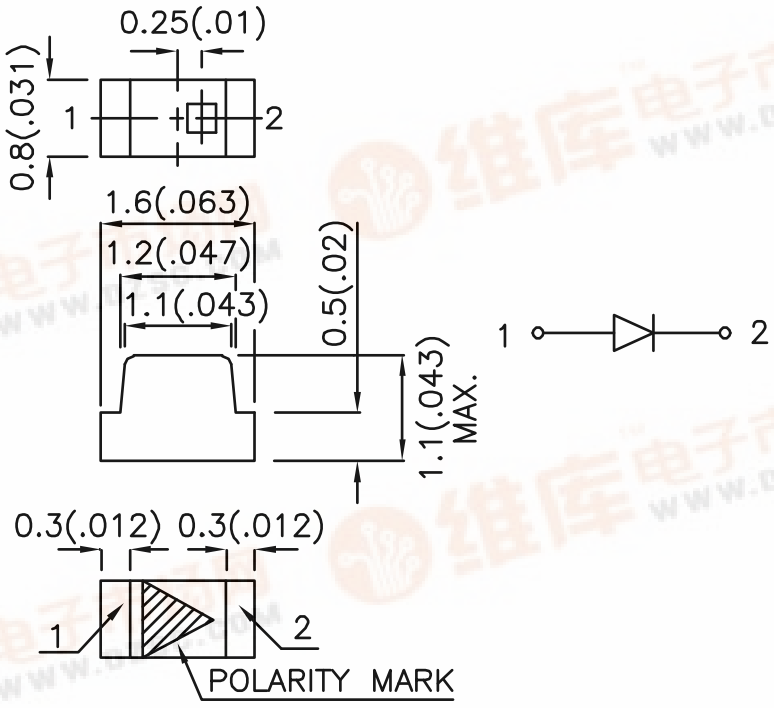
Features

- 1.6mmX0.8mm SMT LED, 1.1mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE: 2000PCS / REEL.
- IN ACCORD WITH Kingbright ENVIRONMENTAL POLICY (DOCUMENT WI-QC-G-0442).
- RoHS COMPLIANT.

Description

The Hyper Red source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.1(0.004") unless otherwise noted.
3.Specifications are subject to change without notice.

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Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
			Min.	Typ.	2θ1/2
AP1608SURCK	HYPER RED (InGaAlP)	WATER CLEAR	50	150	120°

Note:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

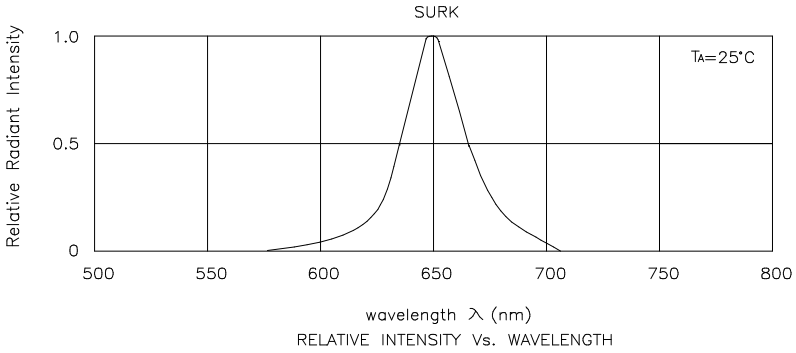
Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	650		nm	I_F=20mA
λD	Dominant Wavelength	Hyper Red	635		nm	I_F=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	I_F=20mA
C	Capacitance	Hyper Red	35		pF	V_F=0V;f=1MHz
V_F	Forward Voltage	Hyper Red	1.95	2.5	V	I_F=20mA
I_R	Reverse Current	Hyper Red		10	uA	V_R = 5V

Absolute Maximum Ratings at T_A=25°C

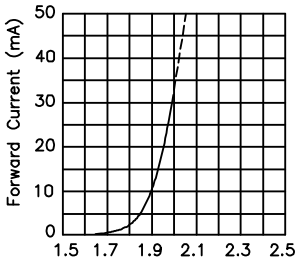
Parameter	Hyper Red	Units
Power dissipation	170	mW
DC Forward Current	30	mA
Peak Forward Current [1]	185	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

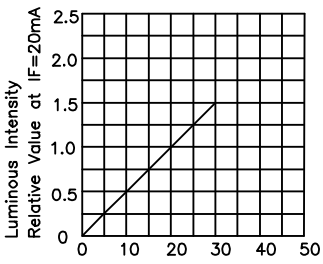


RELATIVE INTENSITY Vs. WAVELENGTH

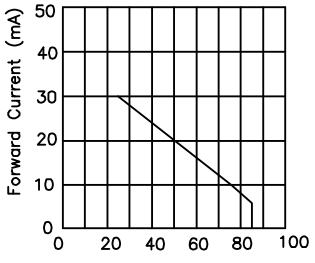
Hyper Red **AP1608SURCK**



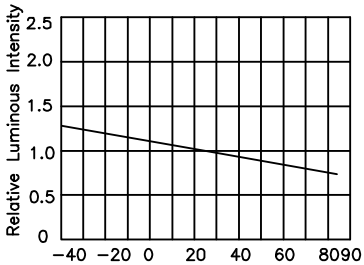
FORWARD CURRENT Vs. FORWARD VOLTAGE



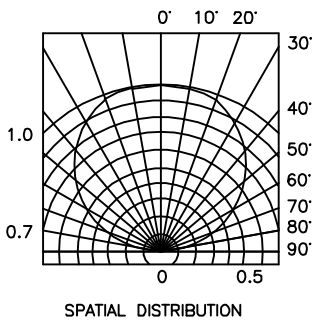
LUMINOUS INTENSITY Vs. FORWARD CURRENT



FORWARD CURRENT DERATING CURVE



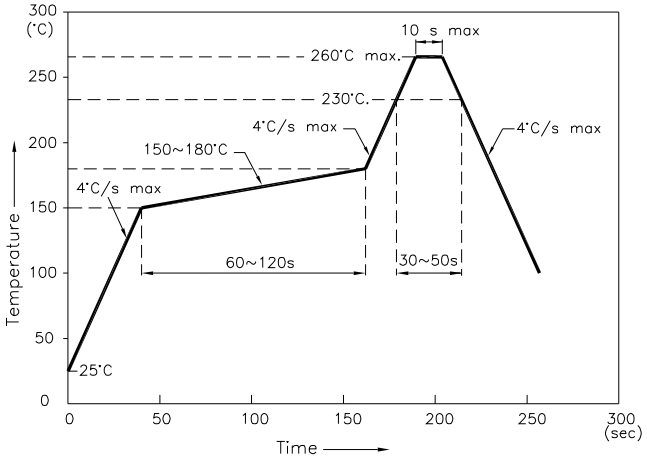
LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

AP1608SURCK

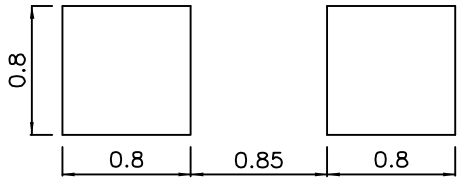
Reflow Soldering Profile For Lead-free SMT Process.



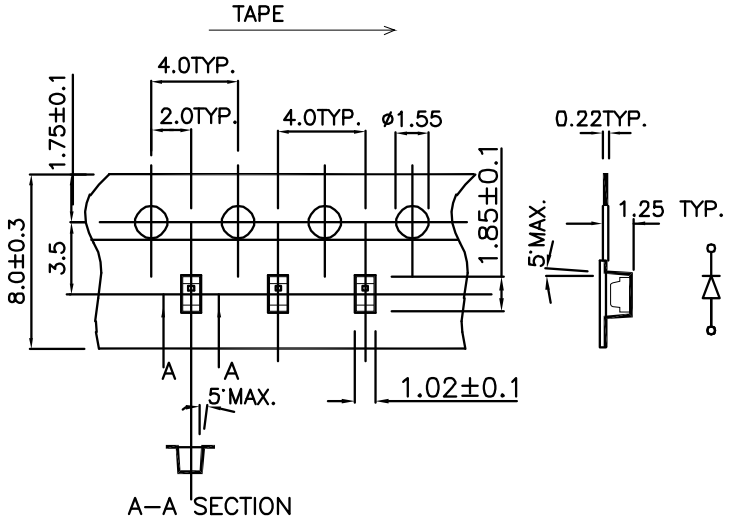
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

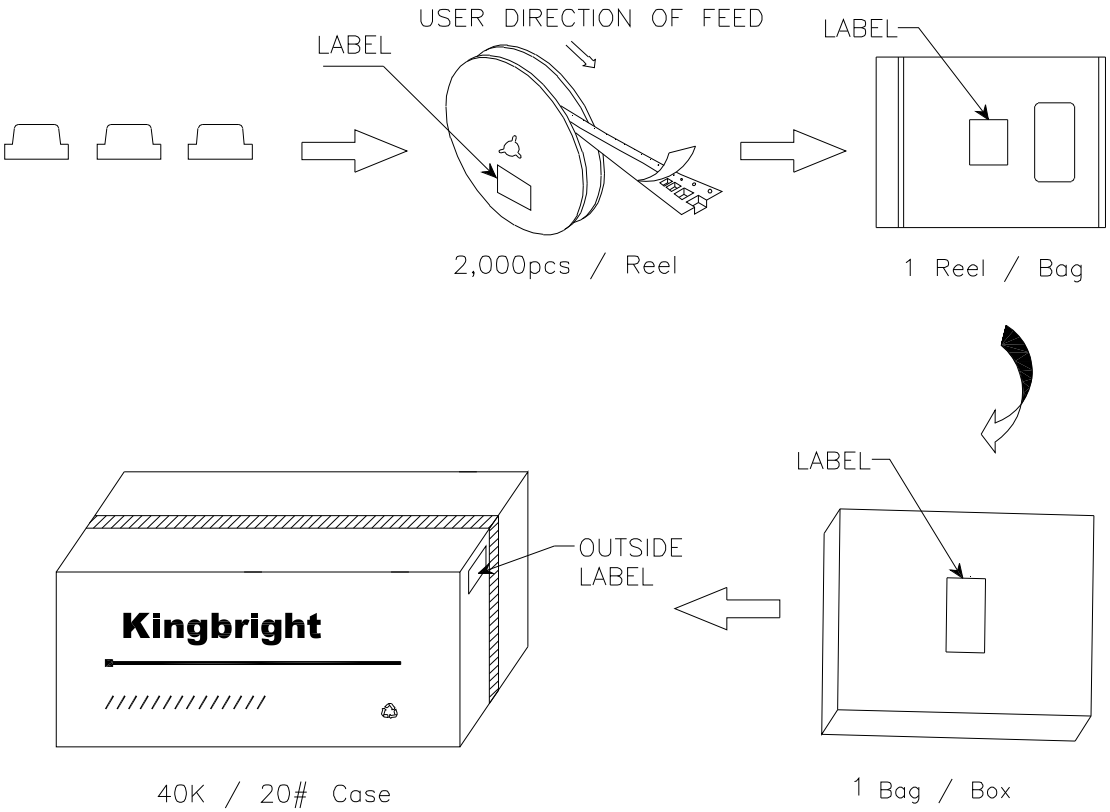
Recommended Soldering Pattern
(Units : mm)

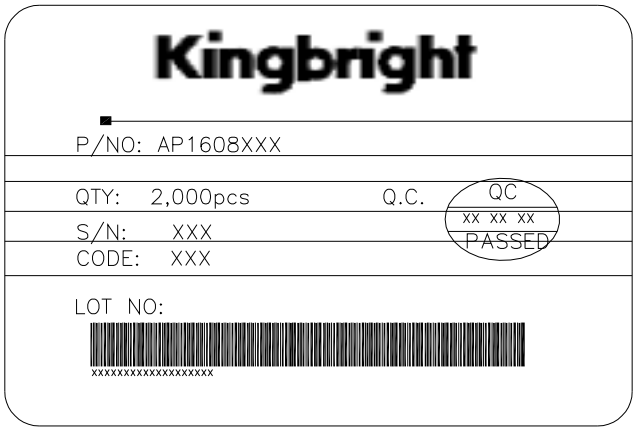


Tape Specifications
(Units : mm)



PACKING & LABEL SPECIFICATIONS **AP1608SURCK**





Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity/ luminous flux or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity/ Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.